

***** BIBLIOGRAPHIC DATA DISPLAY *****

12/01/99 09:26

APPL#: 08/577911 ATTY DCK NO: 95-28 CORRESPONDENCE ADDRESS: CUSTOMER NO. 000000
STEVEN R ORMISTON
FILDT: 12/21/95 ORMISTON KORFANTA DUNBAR & HOLLAND
PATNO: 5686762 802 W. BANNOCK, SUITE 305
ISSDT: 11/11/97 GAU: 2811

CITY: BOISE

ST/CO CODE: ID ZIP/CD: 83701

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EMAIL

DOCK CL/SC: 257/786.000 FOR PR: N

CURR CL/SC: 257/775.000 PARENT: N

TITLE:

SEMICONDUCTOR DEVICE WITH IMPROVED BOND PADS

INVENTORS:

01 LANGLEY

RODNEY C.

(AUTH):

(CITY,ST/CO CODE): BOISE

ID

END OF DISPLAY

PATENT NUMBER: 5686762

ISSUE DATE: 11/11/97

SERIAL NUMBER: 08/577911

FILING DATE: 12/21/95

TITLE: SEMICONDUCTOR DEVICE WITH IMPROVED BOND PADS

APPLICANT: LANGLEY, RODNEY C.

REEL: 007807 FRAME: 0312 MAILROOM DT: 12/21/95 NEW APP FIL RCPT DT: 02/28/96

DATE IN ASSIGNMENTS: 02/29/96 DT MAILED: 05/14/96

DATE RECORDED: 12/21/95 NUMBER OF PAGES: 003

ASSIGNOR: LANGLEY, RODNEY C.

EXC DATE: 12/19/95

ASSIGNEE: MICRON TECHNOLOGY, INC.

PATENT DEPARTMENT

8000 S. FEDERAL WAY, MAIL STOP 507

BOISE, IDAHO 83706

BRIEF:

ASSIGNMENT OF ASSIGNOR'S INTEREST (SEE DOCUMENT FOR DETAILS).

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